**PATENT ASSIGNMENT COVER SHEET**

Electronic Version v1.1  
Stylesheet Version v1.2  
EPAS ID: PAT5304069

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**CORRESPONDENCE DATA**

Fax Number: (215)568-6499  

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

Phone: 215-568-6400  
Email: lgiivigliano@vklaw.com  

**Correspondent Name:** VOLPE & KOENIG, P.C.  
**Address Line 1:** 30 SOUTH 17TH STREET  
**Address Line 2:** SUITE 1800  
**Address Line 4:** PHILADELPHIA, PENNSYLVANIA 19103

**ATTORNEY DOCKET NUMBER:** HKEI TO KEC -SCHEDULE D
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ASSIGNMENT

WHEREAS, Hitachi Kokusai Electric Inc. (Hitachi Kokusai Electric Inc.), a corporation organized and existing under and by virtue of the laws of JAPAN, having an office at 15-12, Nishi-shimbashi 2-chome, Minato-ku, Tokyo, 105-8039, JAPAN, is the owner of the entire right, title, and interest in the U.S. Patents and U.S. Patent Applications (hereinafter "Patent Documents") set forth and identified in Schedule D, by previous assignment.

WHEREAS, Kokusai Electric Corporation, a corporation organized and existing under and by virtue of the laws of JAPAN, having an office at 3-4, Kandakaji-cho, Chiyoda-ku, Tokyo, 101-0045 JAPAN, is desirous of acquiring the entire right, title, and interest in and to the Patent Documents.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, Hitachi Kokusai Electric Inc., intending to be legally bound, does hereby sell, assign, and transfer to Kokusai Electric Corporation and Kokusai Electric Corporation's successors, assigns, and legal representatives the entire right, title, and interest in the Patent Documents, including, but not limited to all divisions and continuations thereof in the United States, and in all letters patent in the United States, including all reissues and reexaminations thereof in the United States, and the right to sue parties other than Hitachi Kokusai Electric Inc. for past infringement.

It is agreed that Hitachi Kokusai Electric Inc. shall be legally bound, upon request of Kokusai Electric Corporation, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the Patent Documents for the benefit of Kokusai Electric Corporation, and to execute all instruments proper to carry out the intent of this instrument.
Hitachi Kokusai Electric Inc. warrants that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 5\textsuperscript{th} day of Dec, 2018.

Hitachi Kokusai Electric Inc.,

By: 

Masaki TANAKA
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